

C1  
cont

a plurality of external electrodes arranged to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element; wherein

each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is provided with a narrow portion and a wide portion.

C2

9. The chip electronic component according to claim 8, further comprising a second case substrate disposed on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

C3

13. A mounting structure of a chip electronic component according to claim 1, wherein a bonding portion defined by a conductive bond does not extend outside of an outer periphery of the chip electronic component as seen from the top of the chip electronic component.

14. A chip electronic component comprising:  
a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;  
an electronic component element having electrodes and defining part of said body of the chip electronic component; and  
a plurality of external electrodes arranged so as to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element;

wherein each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is arranged to have an almost uniform width from one longitudinal end to the other, and satisfy the relation  $L_1 < L_3$ , where  $L_3$  is the

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width of each portion of the external electrodes provided on the lower surface of said body of the chip electronic component, and  $L_1$  is the width of each portion of the external electrodes provided on the at least one side surface of said body of the chip electronic component.